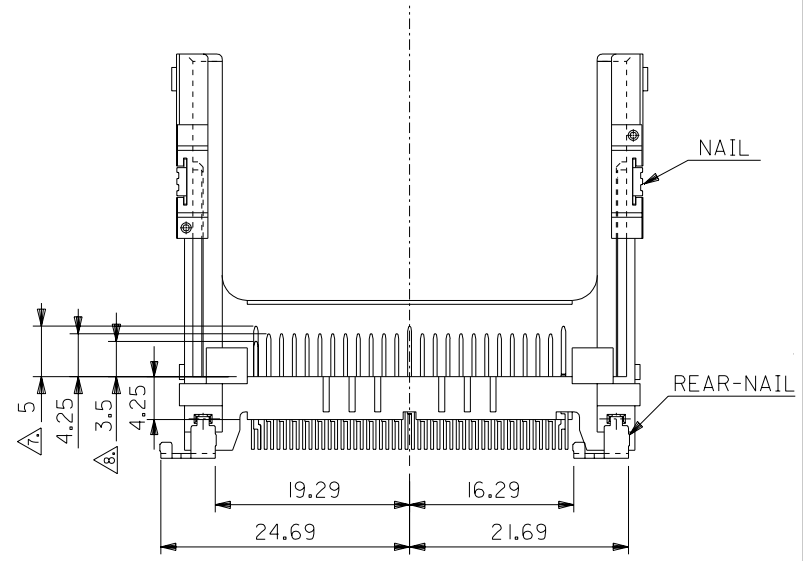
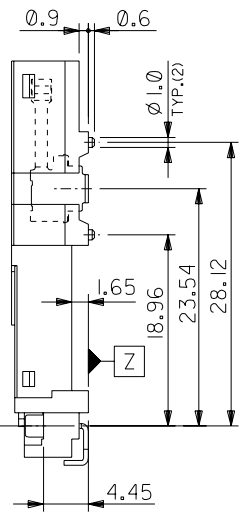
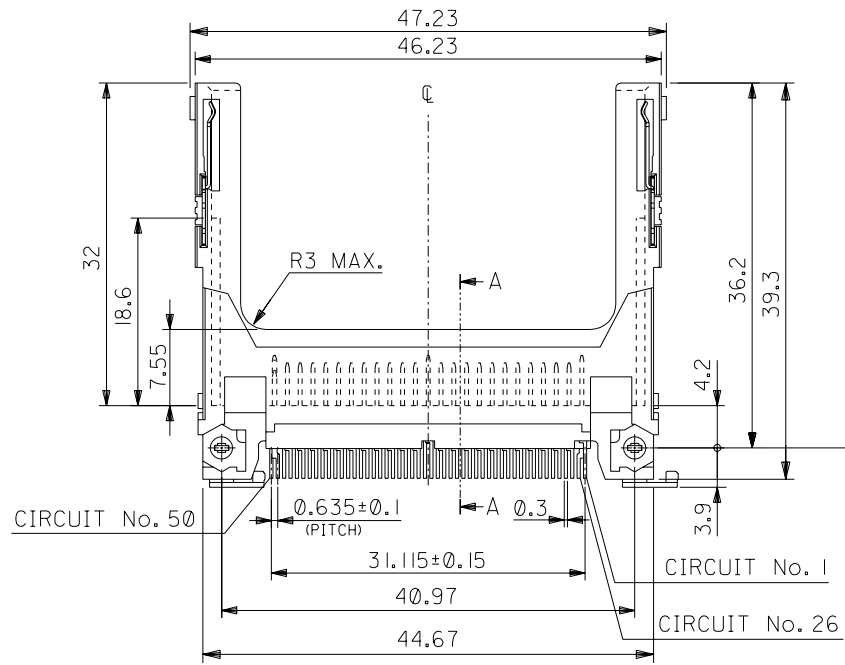
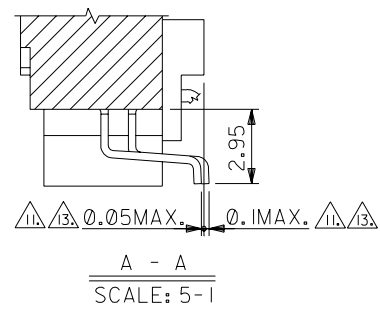
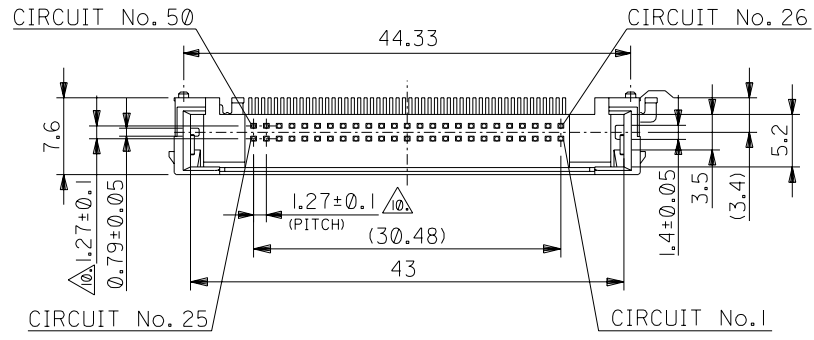


DWG. NO. SD-55358-014



DO NOT SCALE DRAWING

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:
RELEASED EC NO. J2004-3952 DRWN: M.NABEI '04/04/22 CHK: K.TOJO '04/04/22 APPR: M.SASAO '04/04/22			

DESCRIPTION	MATERIAL 材料	FINISH 仕上り	WIRE RANGE 適用層被範囲	INS. RANGE 被覆外径
	SEE NOTES	SEE NOTES	#	#

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	
10 UNDER 未満	±0.2
10 OVER 30 UNDER 以上 未満	±0.25
30 OVER 以上	±0.3
ANGLE 角度	±3°

55358-5028		55358-5029		55358-50**	
HARD TRAY PACKAGE		MATERIAL No.		MODEL No.	
SCALE 2 - 1	DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH	DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input type="checkbox"/> mm <input checked="" type="checkbox"/> INCH ONLY		SHT	REV
DRAWN BY & DATE M.NABEI '04/04/22		TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, NORMAL) -LEAD FREE-			
CHECKED BY & DATE K.TOJO '04/04/22		MATERIAL NO. DRAWING NO. SHEET NO. SEE CHART SD-55358-014 1 OF 2			
APPROVED BY & DATE M. Sasao '04/04/22		MATERIAL NO. DRAWING NO. SHEET NO. SEE CHART SD-55358-014 1 OF 2			
CAD FILENAME SD-55358-014.S01					
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.					
					SIZE B

SD-55358-014.S01

DWG. NO. SD-55358-014

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D

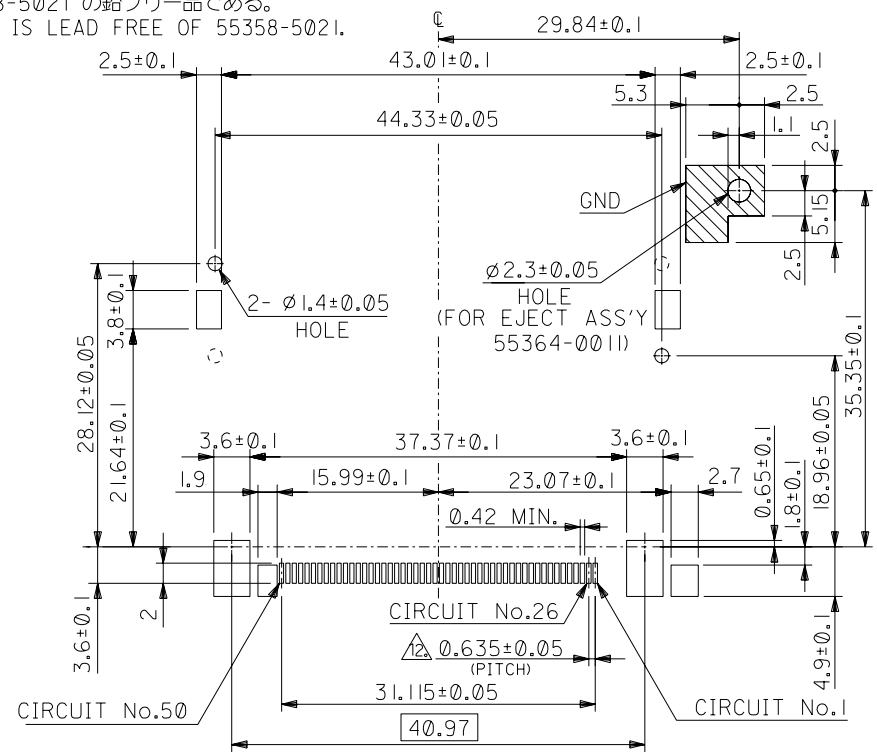
C

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DO NOT SCALE DRAWING

- 注) 1. 材質 MATERIAL  
 ハウジング: ガラス入りLCP UL94V-0  
 HOUSING: LIQUID CRYSTAL POLYMER G.F. UL94V-0  
 ピン: リン青銅  
 PIN: PHOSPHOR BRONZE  
 ネール: リン青銅 (t0.3)  
 NAIL: PHOSPHOR BRONZE (t0.3)  
 リヤネール: リン青銅 (t0.48)  
 REAR-NAIL: PHOSPHOR BRONZE (t0.48)
2. メッキ仕様 PLATING  
 ピン  
 PIN 接点部: パラジウムニッケル下地、金メッキ  
 CONTACT AREA: GOLD OVER PALLADIUM-NICKEL  
 半田付け部: 錫メッキ  
 SOLDER TAIL AREA: TIN  
 下地メッキ: ニッケルメッキ  
 UNDERPLATING: NICKEL OVER ALL  
 ネール  
 NAIL 接点部: 金メッキ  
 CONTACT AREA: GOLD  
 半田付け部: 錫メッキ  
 SOLDER TAIL AREA: TIN  
 下地メッキ: ニッケルメッキ  
 UNDERPLATING: NICKEL OVER ALL  
 リヤネール  
 REAR-NAIL 錫メッキ  
 TIN  
 下地メッキ: ニッケルメッキ  
 UNDERPLATING: NICKEL OVER ALL
3. 推奨基板厚: t=0.8 MIN.  
 RECOMMENDED P.C.B. THICKNESS: t=0.8 MIN.
4. 適合カード厚: 3.3±0.1 (TYPE I) AND 5 MAX. (TYPE II)  
 RECOMMENDED CARD THICKNESS: 3.3±0.1 (TYPE I) AND 5 MAX. (TYPE II)
5. 適合カード幅: 42.8±0.1  
 RECOMMENDED CARD WIDTH: 42.8±0.1
6. ハウジング色: 黒  
 HOUSING COLOR: BLACK
7. 寸法適用極: 1,13,38,50  
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 1,13,38 AND 50.
8. 寸法適用極: 25,26  
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 25 AND 26.
9. ピンの倒れは、ピン根元を基準に全方向へ0.1 MAX.とする。  
 PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED 0.1 WHEN MEASURED FROM PIN BASE.
10. ピン根元に適用する。  
 THIS DIMENSION TO BE MEASURED AT PIN BASE.

11. ソルダータールは、Z面を基準とし上へ0.05下へ0.1の範囲にあり、且ツルダータールの平坦度は、0.1 MAX.とし、テール先端にて測定する。  
 SOLDER TAILS TO BE WITHIN 0.05 UPWARD AND 0.1 DOWNWARD FROM Z-DATUM PLACE, AND COPLANARITY OF SOLDER TAILS TO BE WITHIN 0.1. MEASUREMENT POINT IS SOLDER TAILS TIP.
12. 公差非累積  
 NON-CUMULATIVE
13. テールとネール、リヤネールを併せた平坦度は、0.1 MAX.とする。  
 TOTAL COPLANARITY OF SOLDER TAILS, NAILS AND REAR-NAILS TO BE 0.1 MAX.
14. 本製品は 55358-5021 の鉛フリー品である。  
 THIS PRODUCT IS LEAD FREE OF 55358-5021.



基板推奨寸法  
 RECOMMENDED P.C.B. LAYOUT

EC NO. DRAWN: CHK'G: APPR:		EC NO. DRAWN: CHK'G: APPR:		EC NO. DRAWN: CHK'G: APPR:		EC NO. DRAWN: CHK'G: APPR:		EC NO. DRAWN: CHK'G: APPR:		EC NO. DRAWN: CHK'G: APPR:		EC NO. DRAWN: CHK'G: APPR:		EC NO. DRAWN: CHK'G: APPR:													
DESCRIPTION										MATERIAL 材料		GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		55358-50**		MODEL NO.		DIMENSIONS:		SHT		REV					
SEE NOTES										SEE NOTES		10 UNDER 未滿		±0.2		SCALE 2 - 1		DESIGN UNITS mm INCH		THIRD ANGLE PROJECTION		mm INCH		mm ONLY		REVISE ON CAD ONLY	
SEE NOTES										FINISH 仕上げ		10 OVER 以上		±0.25		DRAWN BY & DATE M.NABEI '04/04/22		TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, NORMAL) -LEAD FREE-									
										30 UNDER 未滿		±0.3		CHECKED BY & DATE K.TOJO '04/04/22		MOLEX INCORPORATED											
										30 OVER 以上		±3°		APPROVED BY & DATE M. Saito '04/04/22		MATERIAL NO.		DRAWING NO.		SHEET NO.		SIZE					
WIRE RANGE 適用電線範囲										—		ANGLE 角度		CAD FILENAME SD-55358-014.S02		—		SD-55358-014		2		B					
INS. RANGE 被覆外径										—				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.						EN-02J(097) MXJ-54							

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SD-55358-014.S02